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(54) **Title:** METHOD FOR MANUFACTURING THICKENED RESIST PATTERN, THICKENING SOLUTION, AND METHOD FOR MANUFACTURING PROCESSED SUBSTRATE

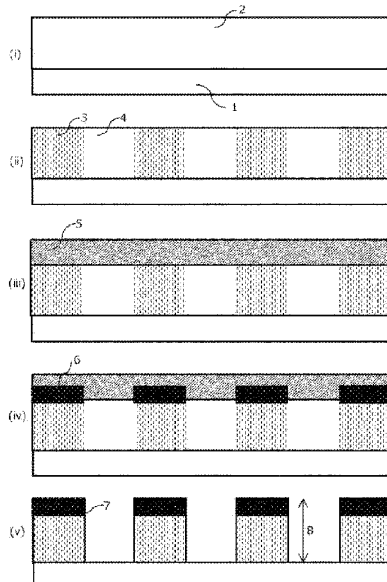


Figure 1

(57) **Abstract:** [Problem] To provide a method for manufacturing a thickened resist pattern. [Means for Solution] A method for manufacturing a thickened resist pattern comprising the following steps: (1) applying a resist composition above a substrate to form a resist layer from the resist composition; (2a) exposing the resist layer; (2b) applying a thickening solution comprising a polymer (A) and a solvent (B) on the resist layer to form a thickening layer; and (3) developing the resist layer and the thickening layer.

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